

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC030N08NS5	**Issued**	22. April 2022
MA#	MA005739145		
Package	PG-TDSON-8-50	**Weight***	106.12 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.43	1.43	14298	14298
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		514	
	non noble metal	iron	7439-89-6	1.090	1.03		10275	
	non noble metal	copper	7440-50-8	44.271	41.71	42.80	417197	428114
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	396	396
encapsulation	organic material	carbon black	1333-86-4	0.081	0.08		762	
	plastics	epoxy resin	-	6.391	6.02		60230	
	inorganic material	silicondioxide	60676-86-0	33.979	32.02	38.12	320209	381201
leadfinish	non noble metal	tin	7440-31-5	1.264	1.19	1.19	11909	11909
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	273	273
solder	noble metal	silver	7440-22-4	0.052	0.05		486	
	non noble metal	tin	7440-31-5	0.103	0.10		972	
	non noble metal	lead	7439-92-1	1.907	1.80	1.95	17976	19434
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		173	
	non noble metal	iron	7439-89-6	0.368	0.35		3465	
	non noble metal	copper	7440-50-8	14.930	14.07	14.44	140694	144375
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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